



**NOTES:**

1. MATERIAL:
  - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP.,UL94V-0.
  - 1.2 CONTACT: COPPER ALLOY.
2. FINISH:
  - 2.1 CONTACT:
    - G: 8u"MIN GOLD ON CONTACT AND 60~150u" TIN ON SOLDER
    - C: 15u"MIN GOLD ON CONTACT AND 60~150u" TIN ON SOLDER
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. SPEC.PLS REFER TO PS-51157-XXXX-XXX
5. PACKAGE PLS REFER TO 51157-XXXX-XX-TRP
6. PART NUMBER

51157-XXX X X-XXX

CKTS

XXX	DIM D	COLOR
001	7.70	NATURAL
002	7.70	BLACK

PLATING

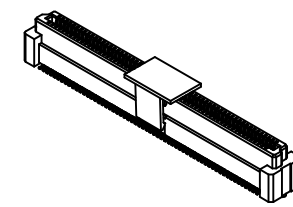
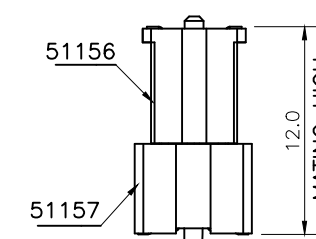
G:8u"MIN GOLD ON CONTACT(LEAD FREE)  
C:15u"MIN GOLD ON CONTACT(LEAD FREE)

PACKING

7:TAPE REEL& WITH COVER



0.10



CKT	DIM A	DIM B	DIM C
40	21.8	15.2	20.2
60	29.8	23.2	28.2
80	37.8	31.2	36.2
100	45.8	39.2	44.2
120	53.8	47.2	52.2
140	61.8	55.2	60.2

<b>QUALITY SYMBOLS</b> MAJOR CRITICAL	DRAWN BY Hu,Yang DATE 21/07/28	
	CHECKED BY DATE 21/07/28	
<b>GENERAL TOLERANCES (UNLESS SPECIFIED)</b> X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	BRAVE DATE 21/07/28	<b>TITLE</b> 0.8mm pitch BTB RECPT Conn. SMT D/R S/T TYPE
	UNITS mm	
SCALE 1:1	SHEET NO. 1 OF 1	REV C
		RFQ NO. N/A
		PART NO. SEE NOTES
		DWG NO. 51157-XXXX-XXX

RECOMMEND PCB LAYOUT

